



## CALL FOR PAPERS



IEEE COMPONENTS, PACKAGING AND  
MANUFACTURING TECHNOLOGY SOCIETY

# International Symposium on Advanced Packaging Materials (APM 2007) October 3-5 2007, San Jose/Silicon Valley, California, USA

The **Advanced Packaging Materials Symposium** (APM 2007) is an international premier technical event on electronic packaging materials organized by the IEEE's Components Packaging and Manufacturing Technology (CPMT) Society and its Santa Clara Valley Chapter. APM 2007 will feature Keynote talks, technical presentations, and exhibits. The Symposium aims to provide leading-edge coverage of developments in all areas of packaging materials and processes. Attendees in the past have included academic researchers, developers, producers, and users of packaging materials from all over the world. APM is also a major packaging materials forum, providing opportunities to network and meet leading experts and exchange up-to-date packaging knowledge in the field.

### Symposium Topics

Paper abstracts are sought on advanced packaging materials in the areas of processing, properties and interfaces, including but not limited to, the following topics:

#### (1) Emerging Technology and Business

- Emerging Packaging Materials Technologies
- Advanced Process Technologies
- Business & Supply Chain Issues

#### (2) Lead-Free, RoHS, Environment

- Lead-Free, RoHS Compliance, Recycle/Disposal
- Design for Environment for Materials

#### (3) Materials

- Cu Low-K
- Underfill & Encapsulant Materials and Processes
- Solders and Bumping
- Substrates, including HDI
- High Thermal Conductivity and Dielectrics
- Reliability
- Adhesives and Compounds
- Solders and Fluxes, Lead free, Bromine free

#### (4) Materials in Packaging Applications

- Advanced Package Types
- Package-to-Board Interconnect
- Applications to 3D Packaging

#### (5) Nano Technology

- materials at nano-scale: packaging & passive materials; optical, soldering materials

APM 2007 is co-located with the 32<sup>nd</sup> International Electronics Manufacturing Technology (IEMT) Symposium. Your APM registration also allows you admission to all IEMT sessions.

### Abstract and Paper Requirements

An abstract of approximately 500 words that summarizes original and previously unpublished work such as historical case studies, research, development and application are welcomed. The abstract shall clearly state the purpose, methodology, results, and conclusions of the work. Key references to prior publications and how the work enhances existing knowledge should be included in the extended abstract. Authors are requested to designate appropriate areas for the purpose of abstract review.

The abstract must be received by **April 30, 2007**. The selection process is competitive and sufficient details need to be included to allow the Technical Program Committee to assess the content of the proposed paper. If selected, papers will be due by **July 31, 2007** and should be a minimum of 6 pages in length (text and graphics). The paper should be non-commercial in nature, and describe significant results from experiments, emphasize new techniques, discuss trends of interest and contain technical and/or appropriate test results. Oral presentations will be limited to 30 minutes including 5 minutes for attendee questions.

### Exhibition

A tabletop exhibition featuring suppliers of materials, equipment, components, software, and services to the electronics industry will also be held at the venue of the symposium. Please inquire for details about exhibiting.

**For More Information, or to submit an abstract,  
please visit our website:**

[www.cpmt.org/apm](http://www.cpmt.org/apm)

### Or contact:

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